HI0805P390R-10

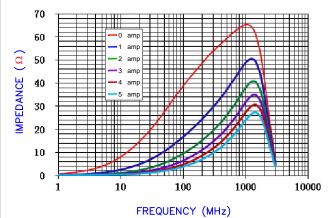
PHYSICAL DIMENSIONS:

A 2.00 [.079] ± 0.20 [.008] B 1.25 [.049] ± 0.20 [.008]

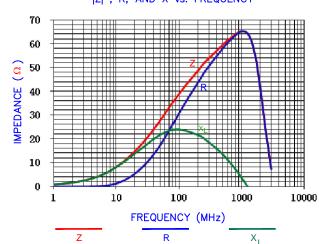
C 0.90 [.035] ± 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]

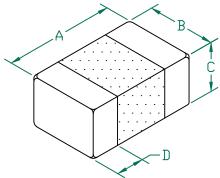
Z vs FREQUENCY IMPEDANCE UNDER DC BIAS



|Z| , R, AND X vs. FREQUENCY



AGILENT E4991A RF Impedance/Material Analyzer AGILENT 16194A.

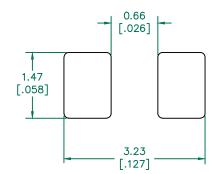


ELECTRICAL CHARACTERISTICS:										
Z @ 100M (Ω)		DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current							
Nominal	39.0									
Minimum	29.3									
Maximum	48.8	0.008	4000 mA							

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPER.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.
- 4. OPERATEING TEMP. RANGE: -40°C~+125°C (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

REFLOW SOLDERING 255 PRE-HEATING SOLDERING 255 ± 5°C [491] 230 [446] 180 [356] 180 [266] 180 [266] 180 [266] 190 190 190 120 SECONDS

RECOMMENDED SOLDERING CONDITIONS

	DIMENSIONS ARE IN mm [INCHE	[S].		This print is the property of Lair Tech. and is loaned in confidence subject to return upon request c with the understanding that no copies shall be made without the written consent of Laird Tech. Al rights to design or invention are reserved.	nd	.a	ir(
				PROJECT/PART NUMBER:	REV	PART TO	PE:	DRAWN BY:
				HI0805P390R-10) A co-		-FIRE	QU
				DATE: 09/05/13	SCALE: NTS		SHEET:	1
A	ORIGINAL DRAFT	09/05/13	QU		00L #			
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Mouser Electronics

Authorized Distributor

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Laird Performance Materials:

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